

Fig. 6 is a cross-sectional view of a structure of an insulating substrate 15 for a semiconductor module according to a fifth preferred embodiment of the present invention. The ceramic plate 1, the first metal plate 2 and the second metal plate 3 of the insulating substrate 15 having the structure based on the insulating substrate 17 shown in Figs. 1 and 2A are of a curved configuration such that the outer peripheral part of the mounting surface for contact with the external heat sink 11 warps upwardly away from the external heat sink 11 a distance L (ranging from 0 to 300  $\mu$ m) above the central part thereof.

#### IN THE CLAIMS

Please cancel claims 9-10.

#### IN THE DRAWINGS

Please rename "Figure 2" to read as – Figure 2A", and insert new Figure 2B as shown on the attached sheet. A Letter Requesting Entry of Drawing Amendment and New Figure is attached hereto.

#### REMARKS

Favorable reconsideration of this application, as presently amended and in light of the following discussion, is respectfully requested.

Claims 1, 3-8, 13-14 are presently pending and active. In this response, claims 9-10 have been canceled without prejudice.